Soldering Methods, Recommended Soldering Method for Moisture-Proof Packing and Flux Cleaning are in the following. Mounting was evaluated with the following profiles in our company, so there was no problem. However, confirm mounting by the condition of your company beforehand.

1. Soldering Temperature Profile of Reflow
   Recommended reflow soldering temperature profile is in the following.

   - **Temperature ramping rate**: 1 to 4°C/s
   - **Pre-heating temperature**
     - **temperature**: 150°C to 180°C
     - **time**: 60 to 120s
   - **Temperature ramp rate**: 1 to 4°C/s
   - **Peak temperature**
     - **temperature**: Lower than 260°C
     - **time**: Shorter than 60s
   - **Temperature ramping rate**: 1 to 6°C/s

   The temperature indicates at the surface of mold package.

2. Soldering Temperature Profile of Flow
   Recommended flow soldering temperature profile is in the following.

   - **Temperature ramping rate**: 1 to 7°C/s
   - **Pre-heating temperature**
     - **temperature**: 80 to 120°C
     - **time**: 60 to 120s
   - **Peak temperature**
     - **temperature**: Lower than 260°C
     - **time**: Shorter than 10s
   - **Temperature ramping rate**: 1 to 7°C/s

   The temperature indicates at solder joint.

3. Soldering Temperature Profile of Iron
   Recommended iron soldering temperature profile is in the following.

   - **At 1 lead**
     - **Temperature**: Lower than 350°C
     - **Time**: within 3s

4. Note
   It is not good for IC’s reliability to keep IC high temperature for long time within limit of recommended ranges. Please finish soldering as soon as possible within limit of recommended ranges. See the next section, “IC storage Conditions and Duration” for Moisture-Proof Packing and Deaeration Packing.